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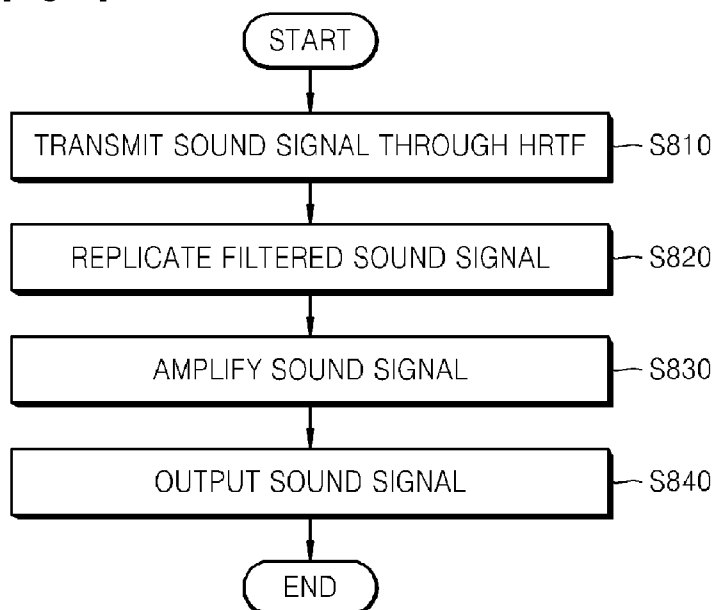
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(54) Title: 3D SOUND REPRODUCING METHOD AND APPARATUS

[Fig. 8]



(57) Abstract: Provided are a three-dimensional (3D) sound reproducing method and apparatus. The method includes transmitting sound signals through a head related transfer filter (HRTF) corresponding to a first elevation, generating a plurality of sound signals by replicating the filtered sound signals, amplifying or attenuating each of the replicated sound signals based on a gain value corresponding to each of speakers, through which the replicated sound signals will be output, and outputting the amplified or attenuated sound signals through the corresponding speakers.



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